



GE Energy

## Functional Testing Specification

Parts & Repair Services  
Louisville, KY

LOU-GED-IS230TSVC2AG01

### Test Procedure for a IS230TSVC2AG01 I/O module assembly

DOCUMENT REVISION STATUS: Determined by the last entry in the "REV" and "DATE" column

REV.	DESCRIPTION	SIGNATURE	REV. DATE
A	Initial Release	J. Francis	05/10/2012
B			
C			

© COPYRIGHT GENERAL ELECTRIC COMPANY

Hard copies are uncontrolled and are for reference only.

PROPRIETARY INFORMATION – THIS DOCUMENT CONTAINS PROPRIETARY INFORMATION OF GENERAL ELECTRIC COMPANY AND MAY NOT BE USED OR DISCLOSED TO OTHERS, EXCEPT WITH THE WRITTEN PERMISSION OF GENERAL ELECTRIC COMPANY.

PREPARED BY J. Francis	REVIEWED BY	REVIEWED BY	QUALITY APPROVAL <i>Charlie Wade</i>
DATE 05/10/2012	DATE	DATE	DATE 5/10/2012

<p><b>LOU-GED-IS230TSVC2AG01</b> <b>Rev A</b></p>	<p><b>g</b></p> <p><b>GE Energy</b> <i>Parts &amp; Repair Services</i> <i>Louisville, KY</i></p>	<p><b>Page 2 of 4</b></p>
---	--	---------------------------

## 1. SCOPE

1.1 This is a functional testing procedure for an IS230TSVC2AG01 I/O module assembly.

## 2. STANDARDS OF QUALITY

2.1 Refer to the current revision of the IPC-A-610 standard for workmanship standards.

## 3. APPLICABLE DOCUMENTS

3.1 The following document(s) shall form part of this specification to the extent specified herein. Unless otherwise indicated, the latest issue shall apply.

3.1.1 Check board's electronic folder for more information

## 4. ENGINEERING REQUIREMENTS

### 4.1 Equipment Cleaning

4.1.1 Equipment should be clean and free of debris prior to applying power unless performing an initial check. Refer to site specific SRA's for cleaning guidelines.

### 4.2 Equipment Inspection

4.2.1 Equipment should be visually inspected for any defects prior to applying power. This inspection should include the following as a minimum:

4.2.1.1 Wires - broken, cracked, or loosely connected

4.2.1.2 Terminal strips / connectors - broken or cracked

4.2.1.3 Components - visually damaged

4.2.1.4 Capacitors - bloated or leaking

4.2.1.5 Solder joints - damaged or cold

4.2.1.6 Circuit board - burned or de-laminated

4.2.1.7 Printed wire runs / Traces - burned or damaged

## 5. EQUIPMENT REQUIRED

5.1 The following equipment is required to perform the process requirements. Equipment may be substituted provided that all accuracy's and test ratios are equivalent or better.

Qty	Reference #	Description
1	*	Fluke 87 DMM (or equivalent)
1		Toffee H
1		Toffee Fixture H188856 for PSVO
1		Toffee Fixture H190013 for WSVO

<p><b>LOU-GED-IS230TSVC2AG01</b> <b>Rev A</b></p>	<p><b>g</b></p> <p><b>GE Energy</b> <i>Parts &amp; Repair Services</i> <i>Louisville, KY</i></p>	<p><b>Page 3 of 4</b></p>
---	--	---------------------------

## 6. TESTING PROCESS

### 6.1 Setup



**Note:** This procedure will be for an entire **IS230TSVC2AG01** assembly. Since we do NOT have a fully functional assembly test, the assembly will be broken down to individually test each sub-assembly separately using its assigned test. The test procedure will be listed for each sub-assembly.

- 6.1.1** Remove the attached **IS220PSVO** modules and test using test procedure **LOU-TOFFEE-IS220PSVOH1A**, referring to Models Database for latest revision of test procedure.
- 6.1.2** Remove the attached **IS210WSVO** modules and test using test procedure **LOU-TOFFEE-IS210WSVO-A**, referring to Models Database for latest revision of test procedure.
- 6.1.3** Remove the **IS200TSVC** card and test using test procedure **LOU-GED-IS200TSVCH2-A**, referring to Models Database for latest revision of test procedure.
- 6.1.4** Test the **IS200JGND** cards using test procedure **LOU-GE-COMPTTEST-G**, referring to Models Database for latest revision of test procedure. The **IS200JGND** cards attached to the unit may be tested without removing cards from unit. These are cards with a terminal block attached and all pins are tied together for shielding purposes.
- 6.1.5** Reassemble unit after all sub-assemblies have been repaired and/or tested successfully.

### 6.2 **\*\*\*TEST COMPLETE\*\*\***

## 7. NOTES

- 7.1** None at this time.

## 8. ATTACHMENTS

### 8.1 Picture of assembly.

